

Description

The AP7N65F/P is silicon N-channel Enhanced VDMOSFETs, is obtained by the self-aligned planar Technology which reduce the conduction loss, improve switching performance and enhance the avalanche energy. The transistor can be used in various power switching circuit for system miniaturization and higher efficiency.

General Features

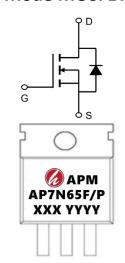
V_{DS} = 650V I_D =7A

 $R_{DS(ON)} < 1.2\Omega \textcircled{0} V_{GS} = 10V \text{ (Type: } 1.0\Omega)$

Application

Uninterruptible Power Supply(UPS)

Power Factor Correction (PFC)





Package Marking and Ordering Information

Product ID	Pack	Marking	Qty(PCS)
AP7N65F	TO-220F-3L	AP7N65F XXX YYYY	1000
AP7N65P	TO-220-3L	AP7N65P XXX YYY	1000

Absolute Maximum Ratings (T_c=25 ℃ unless otherwise noted)

	Parameter	Value		
Symbol		TO-220F TO-220	Unit	
VDSS	Drain-Source Voltage (V _{GS} = 0V)	650	V	
ID	Continuous Drain Current	7	А	
IDM	Pulsed Drain Current (note1)	28	А	
VGS	Gate-Source Voltage	±30	V	
Eas	Single Pulse Avalanche Energy (note2)	247	mJ	
IAR	Avalanche Current (note1)	7	А	
E _{AR}	Repetitive Avalanche Energy note1)	18	mJ	
Po	Power Dissipation (T _C = 25°C)	32.9	W	
TJ, Tstg	Operating Junction and Storage Temperature Range	-55~+150	°C	
RthJC	Thermal Resistance, Junction-to-Case	3.8	°C/W	
RthJA	Thermal Resistance, Junction-to-Ambient	13.3	°C/W	



Electrical Characteristics (T_J=25°C, unless otherwise noted)

Symbol	Parameter	Test Conditions	Min	Тур	Max	Unit
V(BR)DSS	Drain-Source Breakdown Voltage	$V_{GS} = 0V, I_D = 250\mu A$	650	685		V
IDSS	Zero Gate Voltage Drain Current	V _{DS} = 650V, V _{GS} = 0V, T _J =25°C			1	μΑ
IGSS	Gate-Source Leakage	V _{GS} = ±30V			±100	nA
VGS(th)	Gate-Source Threshold Voltage	$V_{DS} = V_{GS}$, $I_D = 250\mu A$	2.0		4.0	V
RDS(on)	Drain-Source On-Resistance (Note3)	V _{GS} = 10V, I _D = 3.5A		1.0	1.2	Ω
C_{iss}	Input Capacitance			1000		
Coss	Output Capacitance	$V_{GS} = 0V$, $V_{DS} = 25V$, $f = 1.0MHz$		101		pF
Crss	Reverse Transfer Capacitance			1.5		
Q_g	Total Gate Charge			22		
Q_{gs}	Gate-Source Charge	V_{DD} =520V, I_D = 7A, V_{GS} = 10V		4.3		nC
Q_{gd}	Gate-Drain Charge			13		
td(on)	Turn-on Delay Time			12		
t _r	Turn-on Rise Time	74 0051/1 74 0 050		26		
td(off)	Turn-off Delay Time	- V _{DD} =325V, I _D = 7A, R _G = 25Ω		29		ns
t _f	Turn-off Fall Time]		27		
IS	Continuous Body Diode Current	T _C = 25 °C			7.0	Α
ISM	Pulsed Diode Forward Current	16 - 25 6			28	Α
V _{SD}	Body Diode Voltage	T _J = 25°C, I _{SD} = 7A, V _{GS} = 0V			1.4	V
trr	Reverse Recovery Time	V _{GS} = 0V,I _S = 7A, di _F /dt =100A		389		ns
Q _{rr}	Reverse Recovery Charge	/µs		2.04		μC

Note:

- 1. The data tested by surface mounted on a 1 inch2 FR-4 board with 2OZ copper.
- 2. The EAS data shows Max. rating . IAS = 4.5A, VDD = 50V, RG = 25 Ω , Starting TJ = 25 $^{\circ}$ C
- 3、The test condition is Pulse Test: Pulse width ≤ 300μ s, Duty Cycle ≤ 1%
- 4. The power dissipation is limited by 150 $^\circ\!\mathrm{C}$ junction temperature
- 5、The data is theoretically the same as ID and IDM, in real applications, should be limited by total power dissipation.



Typical Characteristics

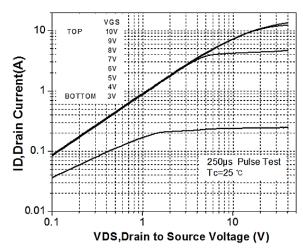


Figure 1. On-Region Characteristics

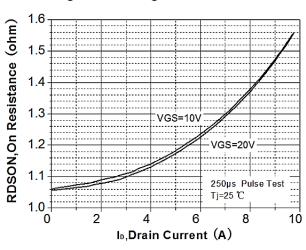


Figure 3. On-Resistance Variation vs Drain Current and Gate Voltage

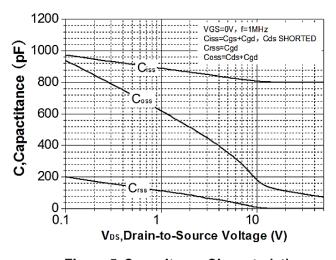


Figure 5. Capacitance Characteristics

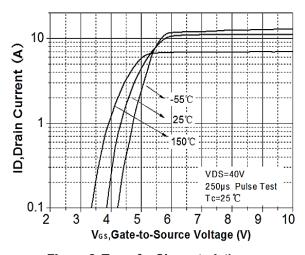


Figure 2. Transfer Characteristics

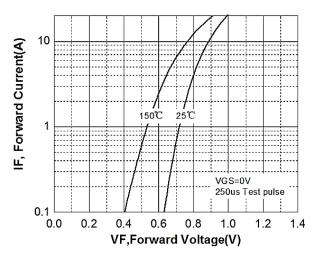


Figure 4. Body Diode Forward Voltage Variation with Source Current and Temperature

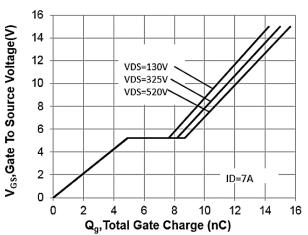


Figure 6. Gate Charge Characteristics





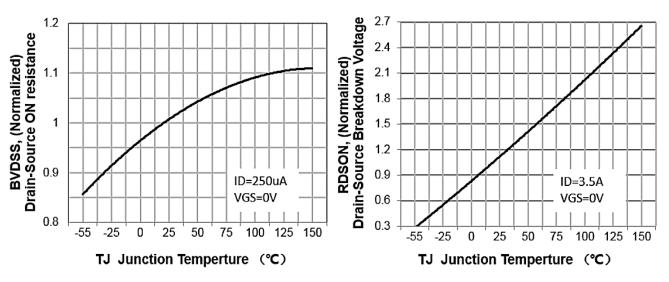


Figure 7. Breakdown Voltage Variation vs Temperature 100 Operate in This Area 100us b,Drain Current(A) ID, Drain Curret(A) is Limited by RDSON 100ms 0.1 1.Ta=25℃ 2.T=150°C 3.Single Pulse 0.01 10 100 1000

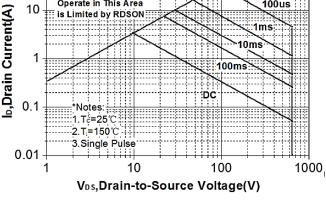


Figure 9. Maximum Safe Operating Area

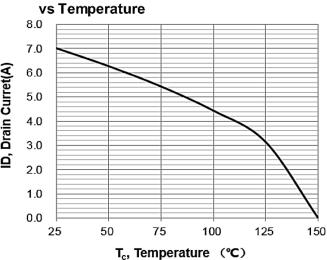


Figure 8. On-Resistance Variation

Figure 10. Maximum Drain Current vs Case Temperature

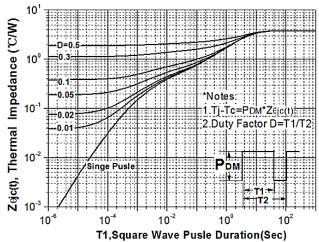
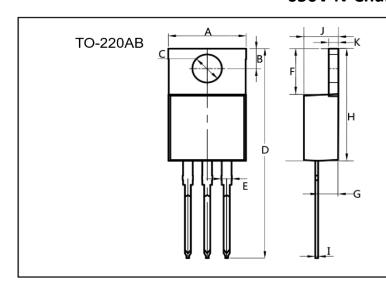
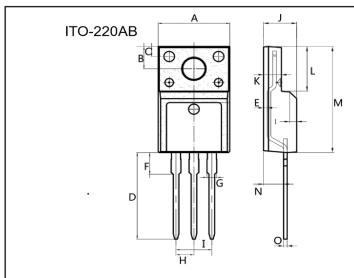


Figure 11. Transient Thermal Response Curve

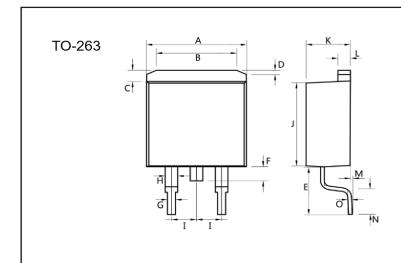




Dim.	Min.	Max.	
Α	10.0	10.4	
В	2.5	3.0	
С	3.5	4.0	
D	28.0	30.0	
E	1.1	1.5	
F	6.2	6.6	
G	2.9	3.3	
Н	15.0	16.0	
I	0.35	0.45	
J	4.3	4.7	
K	1.2	1.4	
All Dimensions in millimeter			



Dim.	Min.	Max.	
Α	9.9	10.3	
В	2.9	3.5	
С	1.15	1.45	
D	12.75	13.25	
Е	0.55	0.75	
F	3.1	3.5	
G	1.25	1.45	
Н	Typ 2.54		
I	Typ 5.08		
J	4.55	4.75	
K	2.4	2. 7	
L	6.35	6.75	
М	15.0	16.0	
N	2.75	3.15	
0	0.45 0.60		
All Dimensions in millimeter			



Min.	Max.		
10.0	10. 5		
7.25	7.75		
1.3	1.5		
0.55	0.75		
5.0	6.0		
1.4	1.6		
0.75	0.95		
1.15	1.35		
Typ 2.54			
8.4	8.6		
4.4	4.6		
1.25	1.45		
0.02	0.1		
2.4	2.8		
0.35	0.45		
All Dimensions in millimeter			
	10.0 7.25 1.3 0.55 5.0 1.4 0.75 1.15 Typ 8.4 4.4 1.25 0.02 2.4 0.35		



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Edition	Date	Change
Rve1.0	2018/1/31	Initial release
Rve1.1	2021/1/05	Reduce RDS(on)

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DMN2080UCB4-7 DMN61D9UWQ-13 US6M2GTR DMN31D5UDJ-7 DMP22D4UFO-7B DMN1006UCA6-7 DMN16M9UCA6-7
STF5N65M6 IRF40H233XTMA1 STU5N65M6 DMN6022SSD-13 DMN13M9UCA6-7 DMTH10H4M6SPS-13 DMN2990UFB-7B
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